



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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SOFT AND LOW ABRASION GAP FILLER

Tputty™ 403 is a single-part, silicone-based thermal gap filler that is soft and low abrasion. Tputty™ 403 is ideal for applications where large or uneven gap tolerances are present. The soft and compliant nature of this material allows for the transfer of little to no pressure on mating parts. Tputty™ 403 provides excellent thermal performance and compliance.

FEATURES AND BENEFITS

- Soft and Compliant
- 2.3 W/mK
- Low Abrasion
- RoHS Compliant
- Available in cartridges (75cc, 180cc, 360cc, 600cc) and pails (1 gallon and 5 gallon)

Packaging Size	Fill Volume	Fill Weight
75cc (2.5 oz)	56cc	140g
180cc (6 oz)	159cc	395g
360cc (12 oz)	326cc	809g
600cc (20 oz)	601cc	1490g
1 gallon	4030cc	10kg
5 gallon	8070cc	20kg

SPECIFICATIONS

PROPERTY	TYPICAL VALUE	METHOD
Construction	Single part silicone based dispensable gap filler	N/A
Color	White	Visual
Thermal Conductivity (w/mK)	2.3	Hot Disk
Flow Rate (75cc taper tip, 0.125" orifice, 40 psi)	29 g/min	Laird Test Method – A16724-00
Density (g/cc)	2.48	Helium Pycnometer
Flammability	V-0	UL 94
Temperature Range	-45 to 150°C	Laird Test Method
Outgassing TML (weight %)	0.05	ASTM E595
Outgassing CVCM (weight %)	0.02	ASTM E595
Dielectric Breakdown	>6000 VAC	ASTM D149
Dielectric Constant @ 1MHz	4.9	ASTM D150
Minimum Bond line Thickness	0.05mm (0.002")	Laird Test Method -A16112-00
Volume Resistivity (ohm-cm)	10 ¹³	ASTM D257

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A16875-00 Tputty 403 DS -053017

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